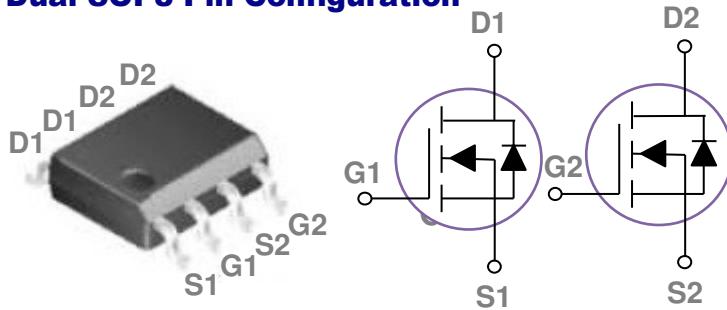


General Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

Dual SOP8 Pin Configuration



| BVDSS | RDS(ON) | ID |
|-------|---------|------|
| 40V | 28mΩ | 8.5A |

Features

- 40V, 8.5A, $RDS(ON) = 28m\Omega$ @ $VGS = 10V$
- Improved dv/dt capability
- Fast switching
- 100% EAS Guaranteed
- Green Device Available

Applications

- MB / VGA / Vcore
- POL Applications
- SMPS 2nd SR

Absolute Maximum Ratings $T_c=25^\circ C$ unless otherwise noted

| Symbol | Parameter | Rating | Units |
|-----------|--|------------|---------------|
| V_{DS} | Drain-Source Voltage | 40 | V |
| V_{GS} | Gate-Source Voltage | ± 20 | V |
| I_D | Drain Current – Continuous ($T_c=25^\circ C$) | 8.5 | A |
| | Drain Current – Continuous ($T_c=100^\circ C$) | 5 | A |
| I_{DM} | Drain Current – Pulsed ¹ | 34 | A |
| EAS | Single Pulse Avalanche Energy ² | 14 | mJ |
| IAS | Single Pulse Avalanche Current ² | 17 | A |
| P_D | Power Dissipation ($T_c=25^\circ C$) | 3.7 | W |
| | Power Dissipation – Derate above $25^\circ C$ | 0.029 | W/ $^\circ C$ |
| T_{STG} | Storage Temperature Range | -55 to 150 | $^\circ C$ |
| T_J | Operating Junction Temperature Range | -55 to 150 | $^\circ C$ |

Thermal Characteristics

| Symbol | Parameter | Typ. | Max. | Unit |
|-----------------|--|------|------|--------------|
| $R_{\theta JA}$ | Thermal Resistance Junction to ambient | --- | 60 | $^\circ C/W$ |

Electrical Characteristics ($T_J=25\text{ }^{\circ}\text{C}$, unless otherwise noted)
Off Characteristics

| Symbol | Parameter | Conditions | Min. | Typ. | Max. | Unit |
|------------|--------------------------------|--|------|------|-----------|---------------|
| BV_{DSS} | Drain-Source Breakdown Voltage | $V_{GS}=0\text{V}$, $I_D=250\mu\text{A}$ | 40 | --- | --- | V |
| I_{DSS} | Drain-Source Leakage Current | $V_{DS}=40\text{V}$, $V_{GS}=0\text{V}$, $T_J=25\text{ }^{\circ}\text{C}$ | --- | --- | 1 | μA |
| | | $V_{DS}=32\text{V}$, $V_{GS}=0\text{V}$, $T_J=125\text{ }^{\circ}\text{C}$ | --- | --- | 10 | μA |
| I_{GSS} | Gate-Source Leakage Current | $V_{GS}=\pm 20\text{V}$, $V_{DS}=0\text{V}$ | --- | --- | ± 100 | nA |

On Characteristics

| | | | | | | |
|---------------------|--|--|-----|------|-----|------------------|
| $R_{DS(\text{ON})}$ | Static Drain-Source On-Resistance ³ | $V_{GS}=10\text{V}$, $I_D=3\text{A}$ | --- | 22.6 | 28 | $\text{m}\Omega$ |
| | | $V_{GS}=4.5\text{V}$, $I_D=2\text{A}$ | --- | 29 | 38 | $\text{m}\Omega$ |
| $V_{GS(\text{th})}$ | Gate Threshold Voltage | $V_{GS}=V_{DS}$, $I_D = 250\mu\text{A}$ | 1.2 | 1.5 | 2.5 | V |
| g_{fs} | Forward Transconductance | $V_{DS}=10\text{V}$, $I_D=1\text{A}$ | --- | 3 | --- | S |

Dynamic and switching Characteristics

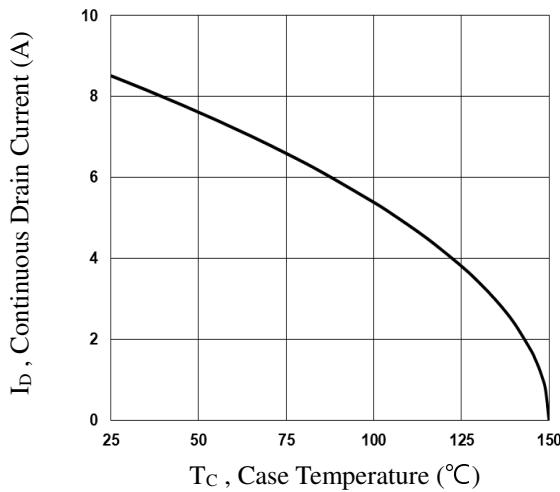
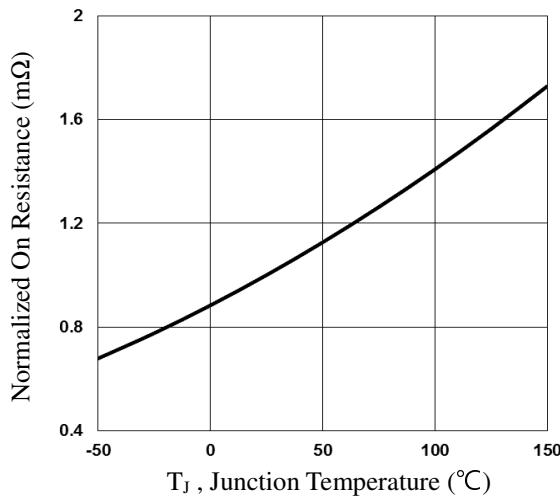
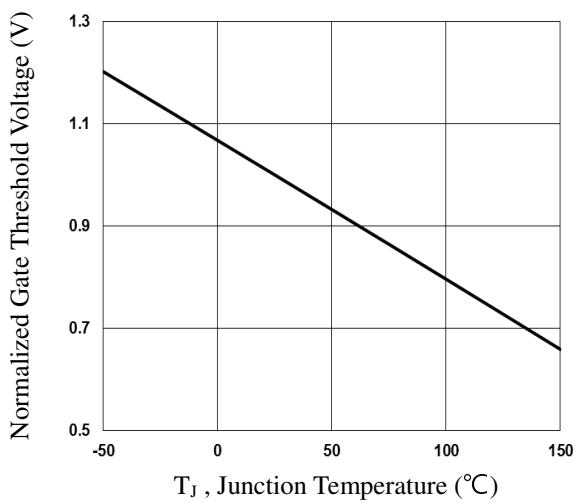
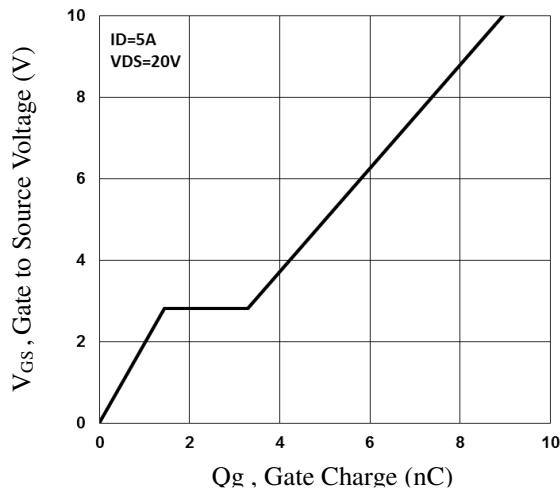
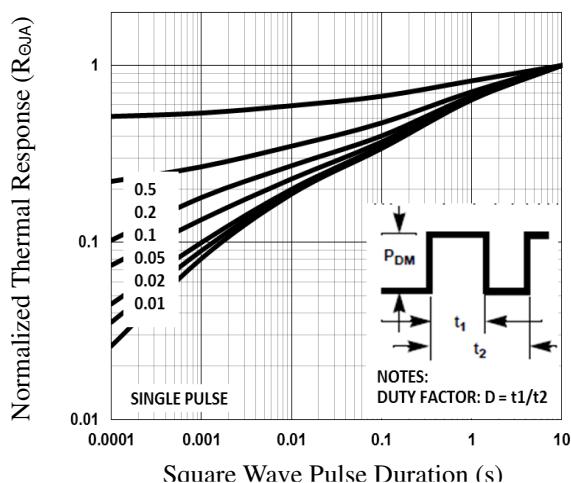
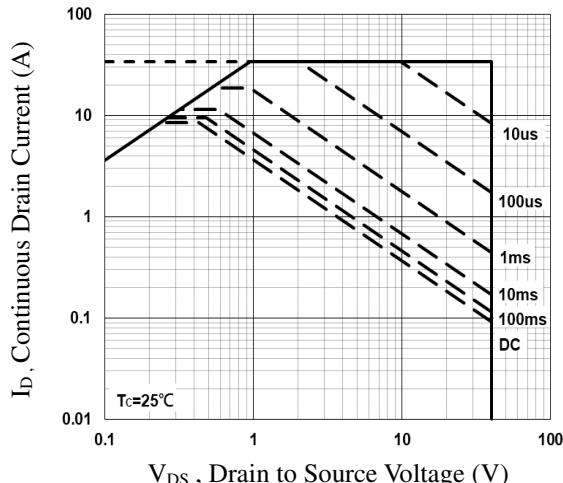
| | | | | | | |
|--------------|-------------------------------------|--|-----|-----|-----|----------|
| Q_g | Total Gate Charge ^{3, 4} | $V_{DS}=20\text{V}$, $V_{GS}=4.5\text{V}$, $I_D=5\text{A}$ | --- | 4.5 | 10 | nC |
| Q_{gs} | Gate-Source Charge ^{3, 4} | | --- | 1.5 | 2.4 | |
| Q_{gd} | Gate-Drain Charge ^{3, 4} | | --- | 1.9 | 5 | |
| $T_{d(on)}$ | Turn-On Delay Time ^{3, 4} | $V_{DD}=20\text{V}$, $V_{GS}=4.5\text{V}$, $R_G=25\Omega$ | --- | 3.2 | 6 | ns |
| T_r | Rise Time ^{3, 4} | | --- | 8.6 | 16 | |
| $T_{d(off)}$ | Turn-Off Delay Time ^{3, 4} | | --- | 18 | 36 | |
| T_f | Fall Time ^{3, 4} | | --- | 6 | 12 | |
| C_{iss} | Input Capacitance | $V_{DS}=25\text{V}$, $V_{GS}=0\text{V}$, $F=1\text{MHz}$ | --- | 420 | 800 | pF |
| C_{oss} | Output Capacitance | | --- | 65 | 120 | |
| C_{rss} | Reverse Transfer Capacitance | | --- | 40 | 80 | |
| R_g | Gate resistance | $V_{GS}=0\text{V}$, $V_{DS}=0\text{V}$, $F=1\text{MHz}$ | --- | 1.2 | 2.4 | Ω |

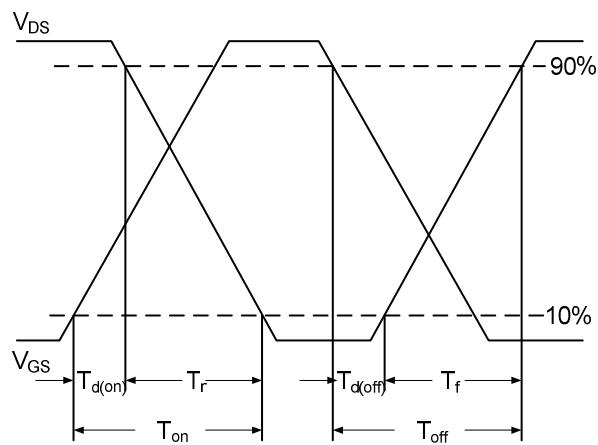
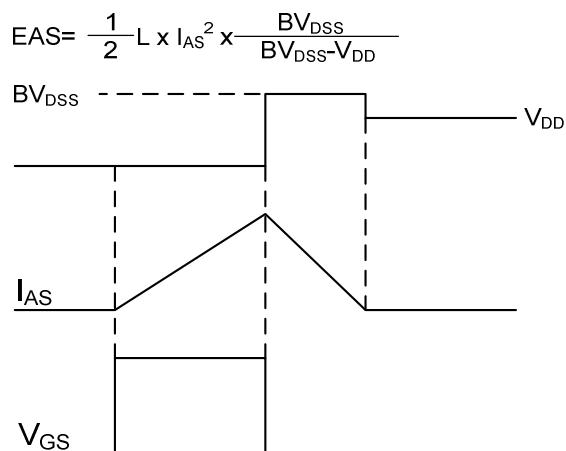
Drain-Source Diode Characteristics and Maximum Ratings

| Symbol | Parameter | Conditions | Min. | Typ. | Max. | Unit |
|----------|------------------------------------|---|------|------|------|------|
| I_s | Continuous Source Current | $V_G=V_D=0\text{V}$, Force Current | --- | --- | 8.5 | A |
| | | | --- | --- | 17 | A |
| V_{SD} | Diode Forward Voltage ³ | $V_{GS}=0\text{V}$, $I_s=1\text{A}$, $T_J=25\text{ }^{\circ}\text{C}$ | --- | --- | 1 | V |

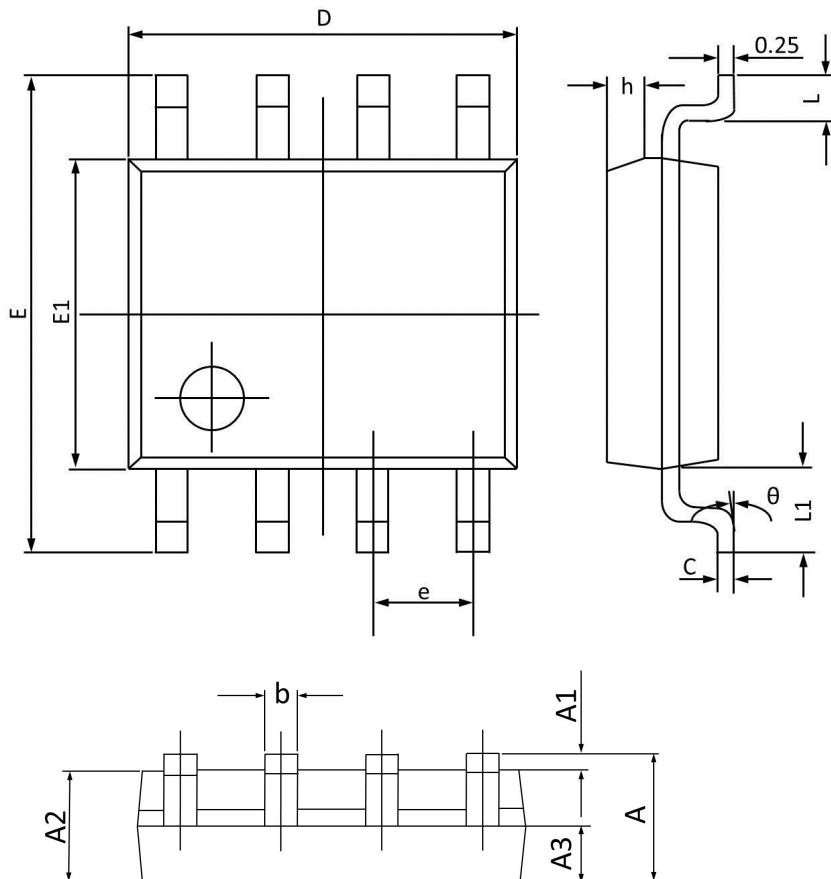
Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. $V_{DD}=25\text{V}$, $V_{GS}=10\text{V}$, $L=0.1\text{mH}$, $I_{AS}=17\text{A}$, $R_G=25\Omega$, Starting $T_J=25\text{ }^{\circ}\text{C}$.
3. The data tested by pulsed , pulse width $\leq 300\text{us}$, duty cycle $\leq 2\%$.
4. Essentially independent of operating temperature.


Fig.1 Continuous Drain Current vs. Tc

Fig.2 Normalized RDSON vs. Tj

Fig.3 Normalized Vth vs. Tj

Fig.4 Gate Charge Waveform

Fig.5 Normalized Transient Response

Fig.6 Maximum Safe Operation Area


Fig.7 Switching Time Waveform

Fig.8 EAS Waveform

SOP8 PACKAGE INFORMATION



| Symbol | Dimensions In Millimeters | | Dimensions In Inches | |
|--------|---------------------------|-------|----------------------|-------|
| | Min | Max | Min | Max |
| A | 1.350 | 1.750 | 0.053 | 0.069 |
| A1 | 0.100 | 0.250 | 0.004 | 0.010 |
| A2 | 1.250 | 1.650 | 0.049 | 0.065 |
| A3 | 0.500 | 0.700 | 0.020 | 0.028 |
| b | 0.380 | 0.510 | 0.015 | 0.020 |
| c | 0.170 | 0.260 | 0.007 | 0.010 |
| D | 4.700 | 5.100 | 0.185 | 0.201 |
| E | 5.800 | 6.200 | 0.228 | 0.244 |
| E1 | 3.700 | 4.100 | 0.146 | 0.161 |
| e | 1.270(BSC) | | 0.050(BSC) | |
| h | 0.250 | 0.500 | 0.010 | 0.020 |
| L | 0.400 | 0.800 | 0.016 | 0.031 |
| L1 | 1.050(BSC) | | 0.041(BSC) | |
| θ | 0° | 8° | 0° | 8° |